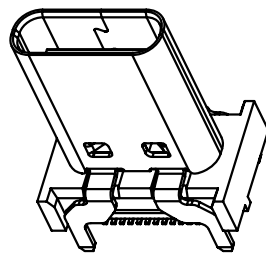
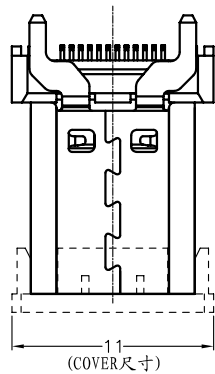
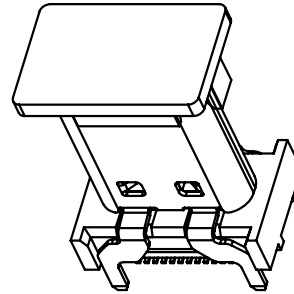


Reference Only

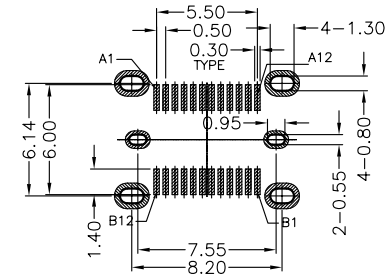
THE PART MEETS TECONN "GP001" COMPLIANCE NEW REV.



WITHOUT COVER



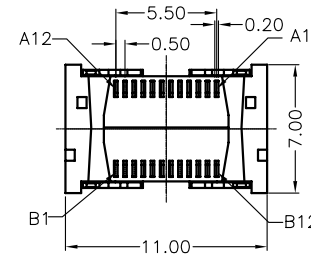
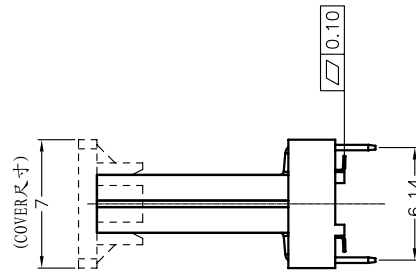
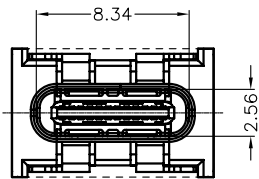
WITH COVER



RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)

TOLERANCE FOR PCB LAYOUT IS ± 0.05

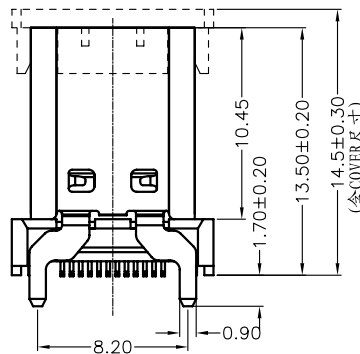
KEEP OUT AREA



A4Q2403-B-XX-R

Mating Area plating

01: Au 1u"Min.
03: Au 3u"Min.
05: Au 5u"Min.
10: Au 10u"Min.
15: Au 15u"Min.
30: Au 30u"Min.



- 1.Contact Resistance:40mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:100M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force: 5~20N
Unmating Force: 8~20N;
6~20N AFTER TEST;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose	Remark
1	Shell	Stainless Steel	Ni:30u" Min.	
2	GND Plate	Stainless Steel		
3	Mid Plate	Stainless Steel		
4	Top Contact	Copper Alloy	Mating Area: See P/N	
5	Bottom Contact	Copper Alloy	Solder Tails: Matt Tin	
6	Insulator	High Temperature Plastic	UL 94V-0	Black

X. ± 0.30	APPD:	Henry	TITLE:	 泰康电子 TECONN	
.X ± 0.20	CHKD:	Lebon	USB 3.1 TYPE C FEMALE VERTICAL H13.5mm SMT TYPE		
.XX ± 0.15	DR:	Lei	PART NO:		
.XXX± 0.10			A4Q2403-B-XX-R		
X° ± 2°					
.X° ± 1.5°					
	UNITS:	SCALE:	DWG NO:	CUSTOMER DRAWING	SHEET:10F1
	mm	3:1	C-A4Q2403-B-XX-R		REV: X1

REV	ECN NO	DESCRIPTION	DESIGN	DATE
A	TE2018-XXXX	New Drawing	Lei	2018/03/06